

View Online at <https://aerobasegroup.com/nsn/8030-01-629-4132>

**Physical Form:**

Solid

**Usage Design:**

For extremely low thermal impedance at thinner bondline thicknesses (sometimes below 1 mil)

**Curing Method:**

Heat

**Product Name:**

Thermal grease

**Special Features:**

Silicone based thermal grease that conducts heat between hot component and a heat sink or enclosure; fills interface variable tolerances in electronics assemblies and heat sink applications; non curing, dispensable, highly conformable materials require no cure cycle, mixing or refrigeration; thermally stable and require virtually no compressive force to deform under assembly pressure; meet the need for high power applications requiring material with bond line thickness and high conductivity; ideal for rework and field repair situations; operating temp range-minus 55c to 200c

**Color:**

Gray, light

**Material:**

Silicone

**Shelf Life:**

N/a

**Unit Of Measure:**

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**Demilitarization:**

No

**Fig:**

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